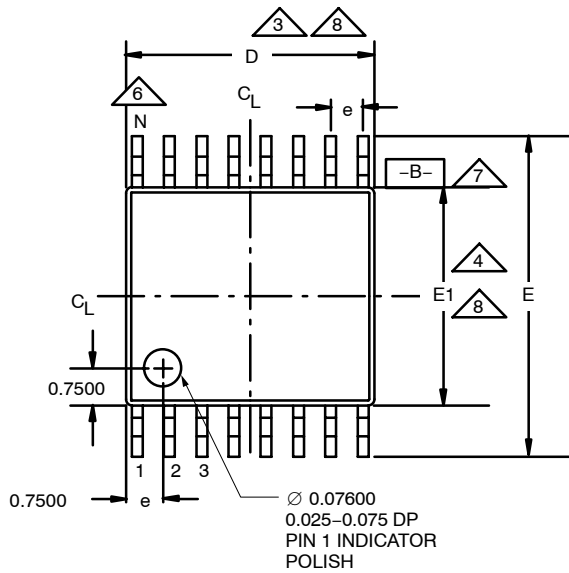
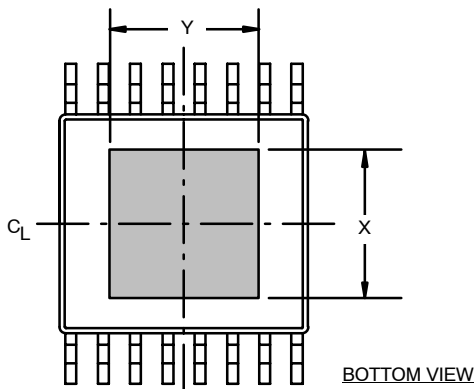
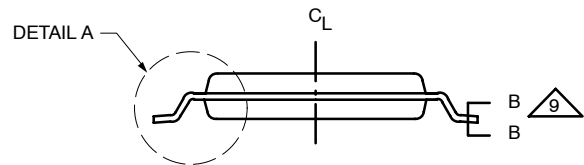
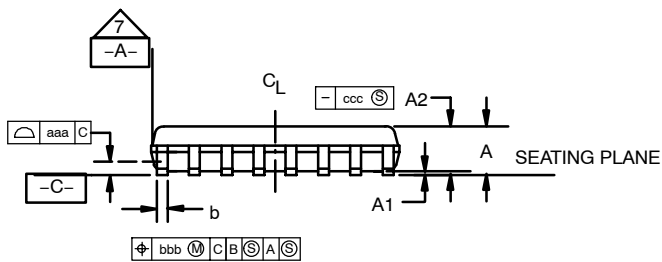
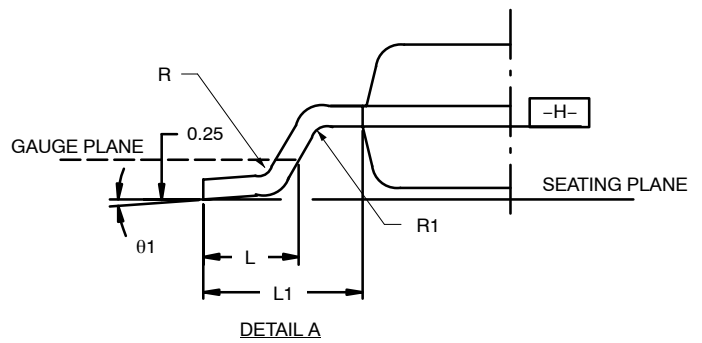


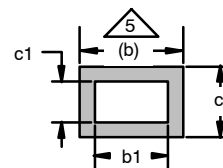
POWER IC THERMALLY ENHANCED PowerPAK® TSSOP: 14/16-LEAD



TOP VIEW



EXPOSED PAD





POWER IC THERMALLY ENHANCED PowerPAK® TSSOP: 14/16-LEAD

Dim	MILLIMETERS			INCHES*		
	Min	Nom	Max	Min	Nom	Max
A	–	–	1.20	–	–	0.0472
A₁	0.025	–	0.100	0.001	–	0.0039
A₂	0.80	0.90	1.05	0.0315	0.0354	0.0413
b	0.19	–	0.30	0.0075	–	0.0118
b₁	0.19	0.22	0.25	0.0075	0.0087	0.0098
c	0.09	–	0.20	0.0035	–	0.0079
c₁	0.09	–	0.16	0.0035	–	0.0063
D	4.9	5.0	5.1	0.1929	0.1968	0.2008
e	0.65 BSC			0.0256 BSC		
E	6.2	6.4	6.6	0.2441	0.2520	0.2598
E₁	4.3	4.4	4.5	0.1693	0.1732	0.1772
L	0.45	0.60	0.75	0.0177	0.0236	0.0295
L₁	1.0 REF			0.0394 REF		
R	0.09	–	–	0.0035	–	–
R₁	0.09	–	–	0.0035	–	–
θ₁	0	–	0	0	–	0
N (14)	14			14		
N (16)	16			16		
X	2.95	3.0	3.05	0.116	0.118	0.120
Y (14)	3.15	3.2	3.25	0.124	0.126	0.128
Y (16)	2.95	3.0	3.05	0.116	0.118	0.120
aaa	0.10			0.0039		
bbb	0.10			0.0039		
ccc	0.05			0.0020		
ddd	0.20			0.0079		
ECN: S-50568—Rev. B, 04-Apr-05 DWG: 5913						

*Dimensions are in mm converted to inches.

NOTES:

1. All dimensions are in millimeters (angles in degrees).
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. Dimension “D” does not include mold flash, protrusions or gate burrs.
4. Dimension “E₁” does not include internal flash or protrusion.
5. Dimension “b” does not include Dambar protrusion.
6. “N” is the maximum number of lead terminal positions for the specified package length.
7. Datums \boxed{A} and \boxed{B} to be determined at datum plane \boxed{H} .
8. Dimensions “D” and “E₁” are to be determined at datum plane \boxed{H} .
9. Cross section B-B to be determined at 0.10 to 0.25 mm from the lead tip.
10. Refer to JEDEC MO-153, Issue C., Variation ABT.
11. Exposed pad will depend on the pad size of the L/F.